

rinsing solution containing a rinsing agent and an inhibiting agent prior to removing the edge bead.

2. The method of claim 1, wherein the concentration of the inhibiting agent is between about 0.1% and about 5.0% by volume.
3. The method of claim 2, wherein the concentration of the inhibiting agent is between about 0.3% and about 1.0% by volume.
4. The method of claim 1, wherein the rinsing agent is deionized water and the inhibiting agent is at least one of benzotriazol and toluenetriazol.
5. The method of claim 1, wherein the inhibiting agent forms a protective film on the substrate surface that operates to prevent corrosion thereof.
6. The method of claim 1, further comprising drying the substrate surface through a spin dry process, where an isopropyl alcohol solution is applied to the substrate surface during the spin dry process.
7. (Amended) A method for removing an edge bead from a substrate surface, comprising:
 - rinsing the substrate surface to remove residue chemicals therefrom;
 - applying an edge bead removal solution to the substrate surface; and
 - spin rinse drying the substrate surface to remove residue edge bead removal solution,wherein the [rinsing] spin rinse drying step includes applying an inhibitor solution to the substrate surface to prevent corrosion thereof.
8. The method of claim 7, wherein the inhibitor solution comprises a chemical solution calculated to chemically react with the substrate surface to form a protective barrier layer on the substrate surface.
9. The method of claim 7, wherein the inhibitor solution includes at least one of benzotriazol and toluenetriazol.
10. The method of claim 7, wherein the concentration of the inhibitor solution is between about 0.1% and about 5.0% by volume.

11. The method of claim 7, wherein the concentration of the inhibitor solution is between about 0.3% and about 1.0% by volume.
12. The method of claim 7, wherein the inhibitor solution is mixed with the rinsing solution for application during rinsing.
13. The method of claim 8, wherein the protective barrier layer may be removed with an etchant.
14. (Amended) An apparatus for removing an edge bead from a substrate, comprising:
- a substrate support member configured to support [a] the substrate in a face down position for processing;
 - means for dispensing an edge bead removal solution onto an edge bead of [a] the substrate positioned on the substrate support member;
 - means for rinsing a surface of the substrate, the means for rinsing being positioned in the substrate support member; and
 - means for applying an inhibitor to the surface of the substrate, the means for applying an inhibitor being positioned in the substrate support member.
15. The apparatus of claim 14, wherein the means for applying an inhibitor further comprises an inhibitor dispensing aperture formed into an upper surface of the substrate support member, the inhibitor dispensing aperture being in fluid communication with an inhibitor source.
16. The apparatus of claim 15, wherein the inhibitor dispensing aperture is positioned in a central portion of the upper surface.
17. The apparatus of claim 14, wherein the substrate support member is rotatable.
18. The apparatus of claim 14 wherein the means for rinsing comprises a fluid dispensing aperture positioned in a central portion of an upper surface of the substrate support member.
19. The apparatus of claim 14, wherein the means for rinsing and the means for applying an inhibitor comprise a shared aperture formed into an upper surface of the